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ABSTRACT

SELF-SIPHONING CMP TOOL DESIGN FOR APPLICATION SUCH AS COPPER CMP AND LOW-K DIELECTRIC CMP

A new method is provided for the polishing of semiconductor surfaces such as the surface of a substrate, the surface of deposited copper and the surface of low-k layers of dielectric. The polishing method and apparatus of the invention comprise a new slurry delivery design whereby at least two different slurries can be independently controlled and mixed for delivery to a slurry container. The slurry container is in direct physical contact with a polishing pad, providing for the mixed slurry to be distributed over the surface of the polishing pad.

Figure 3

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